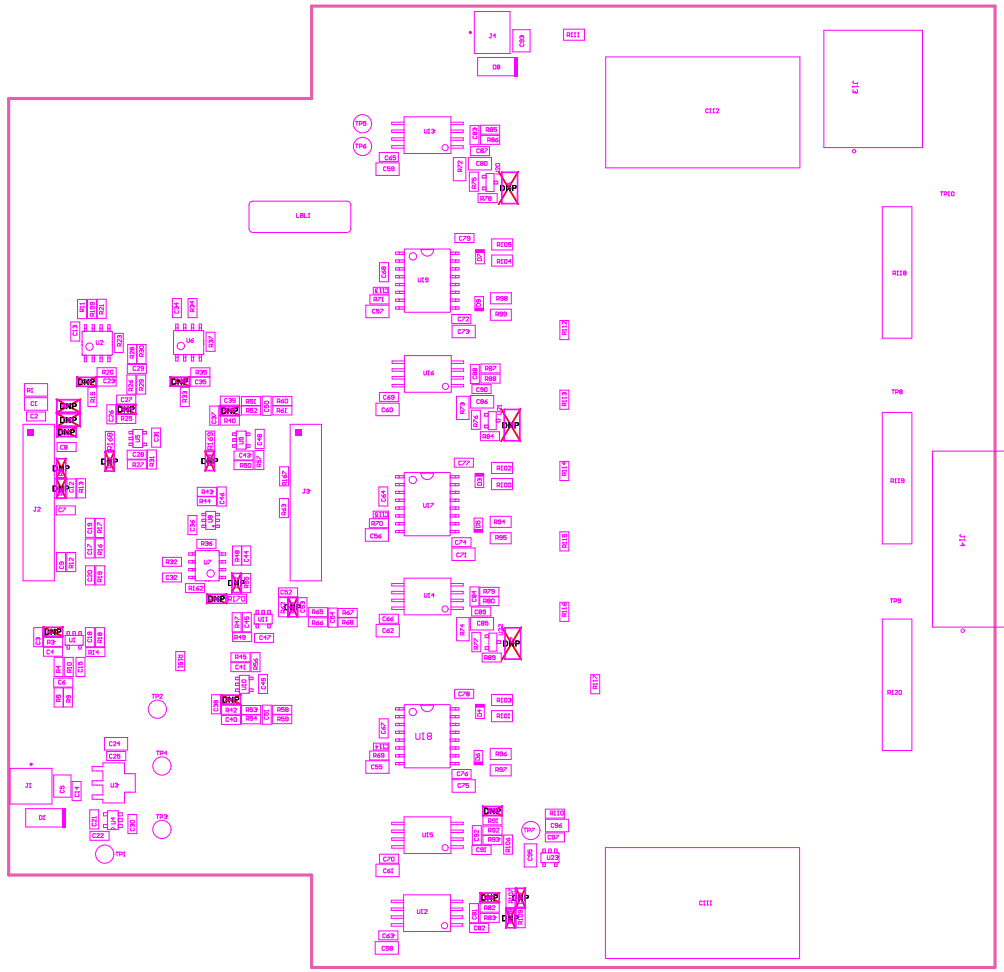
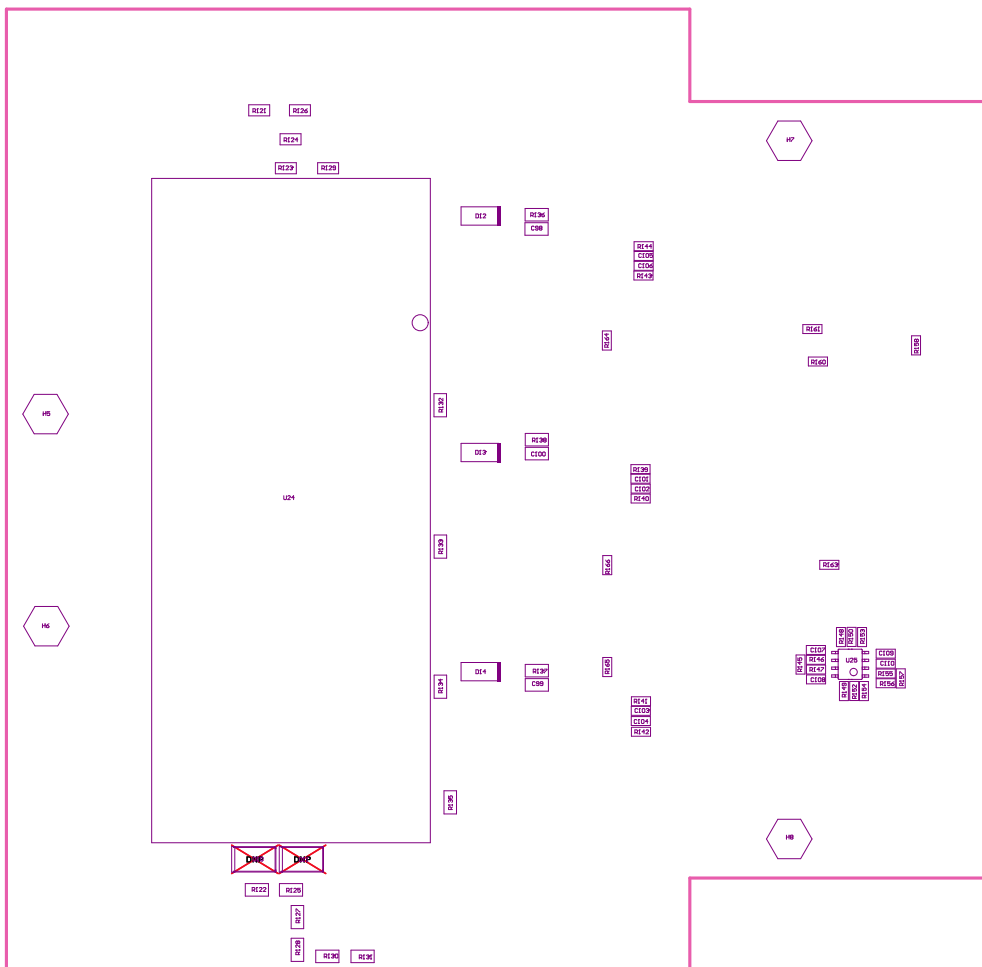


- 221 ■ Internal label in stickered box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the POP schematic.
- 222 ■ These assemblies are ESD sensitive. ESD precautions shall be observed.
- 223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.  
 ASSEMBLY URGENT! D02

ALL PARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDM-Q154C	REV:	E1	SNV REV:	Not In VersionControl
LAYER NAME =	TS Assembly Top	TID #:	TIDM-Q154C			
Top Assembly Drawing	GENERATED:	1	23-Nov-17	3:36:51 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY DIRECTION

PCB VIEWED FROM BOTTOM SIDE	BOARD #	TIDN-02541	REV	ET	SAR REV	Not in versioncontrol
LAYER NAME = H6 Assembly Bottom	TID #1	TIDN-02541	JONKNE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED	23-Nov-17	3:26:52 PM			

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